

1765



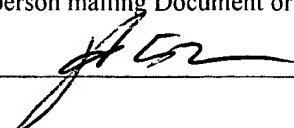
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited
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Amendment, Commissioner for Patents,
Washington, D.C. 20231 on April 17, 2003
(Date of Deposit)

Harold C. Moore

Name of person mailing Document or Fee


Signature

April 17, 2003

Date of Signature

Re:	Application of:	Charles E. May
	Serial No.:	09/943,196
	Filed:	August 30, 2001
	For:	Arrangement and Method for Fabricating A Semiconductor Wafer
	Group Art Unit:	1765
	Examiner:	Lynette T. Umez-Eronini
	Our Docket No.:	01-146 (1003-0606)

TRANSMITTAL OF RESPONSE TO OFFICE ACTION

Please find for filing in connection with the above patent application the
following:

1. Response to Office Action; and
2. One (1) return post card.

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GROUP 1700

* The fee has been calculated as shown below.

CLAIMS AS AMENDED				
	Claims Remaining After Amendment	Highest No. Paid For	Fee Calculation	Addit Fee
Total Claims	17	20	0 X 18	\$ 0.00
Independent Claims	2	3	0 X 84	\$ 0.00
Total Additional Fee Required				\$ 0.00

Please charge any fee deficiency, or credit any overpayment, to Deposit Account No. 13-0014; but not to include any payment of issue fees.

Respectfully Submitted,

MAGINOT, MOORE & BOWMAN



April 17, 2003

Harold C. Moore
Registration No. 37,892
Bank One Center/Tower
111 Monument Circle, Suite 3000
Indianapolis, Indiana 46204-5115

Enclosures



#3/A
4/24/03

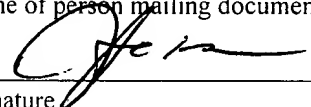
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RESPONSE TO OFFICE ACTION

Sir:

Please charge any fee deficiency or credit any overpayment to Deposit Account

No. 13-0014. In response to the Office Action dated January 17, 2003 for the above-
identified patent application, please amend the application as follows: